

HOSTAFORM® LX90Z XAP®2 ECO-B

HOSTAFORM®

Hostaform® acetal copolymer grade LX90Z XAP®2 is UV stabilized material available in a range of molded in metallic colors generally for automotive interior applications. In addition, Hostaform® LX90Z XAP®2 has lower volatile emissions as required for some automotive interiors. Besides material, optimal finish for specialty metallic parts is dependent on proper drying, gate design, knit line locations, and special processing. Please contact Celanese Technical Service for assistance with your application. Low Emission Performance [VDA-275] < 5 PPM

ECO-B: Hostaform® ECO-B is a POM-Copolymer with the same properties and performance as standard grades but produced with sustainability in mind. Using a mass-balance approach, biogenic feedstocks are used to offset the use of fossil-based raw materials and decrease greenhouse gas emissions. The process is audited and certified according to the ISCC Plus mass balance approach.

Product information

Resin Identification	POM	ISO 1043
Part Marking Code	>POM<	ISO 11469

Rheological properties

Moulding shrinkage, parallel	2.3 %	ISO 294-4, 2577
Moulding shrinkage, normal	1.4 %	ISO 294-4, 2577

Typical mechanical properties

Tensile modulus	2700 MPa	ISO 527-1/-2
Tensile stress at yield, 50mm/min	54 MPa	ISO 527-1/-2
Tensile strain at yield, 50mm/min	8 %	ISO 527-1/-2
Flexural modulus	2900 MPa	ISO 178
Flexural stress at 3.5%	67 MPa	ISO 178
Charpy notched impact strength, 23 °C	4 kJ/m ²	ISO 179/1eA
Charpy notched impact strength, -30 °C	4 kJ/m ²	ISO 179/1eA
Poisson's ratio	0.422	

Thermal properties

Melting temperature, 10 °C/min	165 °C	ISO 11357-1/-3
Temperature of deflection under load, 1.8 MPa	90 °C	ISO 75-1/-2
Temperature of deflection under load, 0.45 MPa	147 °C	ISO 75-1/-2
Coefficient of linear thermal expansion (CLTE), parallel	90 E-6/K	ISO 11359-1/-2
Coefficient of linear thermal expansion (CLTE), normal	100 E-6/K	ISO 11359-1/-2

Physical/Other properties

Humidity absorption, 2mm	0.2 %	Sim. to ISO 62
Water absorption, 2mm	0.75 %	Sim. to ISO 62
Density	1430 kg/m ³	ISO 1183

Injection

Drying Recommended	no
Drying Temperature	100 °C
Drying Time, Dehumidified Dryer	3 - 4 h
Processing Moisture Content	≤0.2 %
Melt Temperature Optimum	190 °C

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Min. melt temperature	180 °C
Max. melt temperature	195 °C
Screw tangential speed	≤0.3 m/s
Mold Temperature Optimum	110 °C
Min. mould temperature	100 °C
Max. mould temperature	125 °C
Hold pressure range	60 - 120 MPa
Back pressure	4 MPa

Characteristics

Processing	Injection Moulding, Extrusion
Delivery form	Pellets
Additives	Release agent
Special characteristics	Light stabilised or stable to light, U.V. stabilised or stable to weather, Specialty appearance, Low emissions
Sustainability	Bio-Content

Additional information

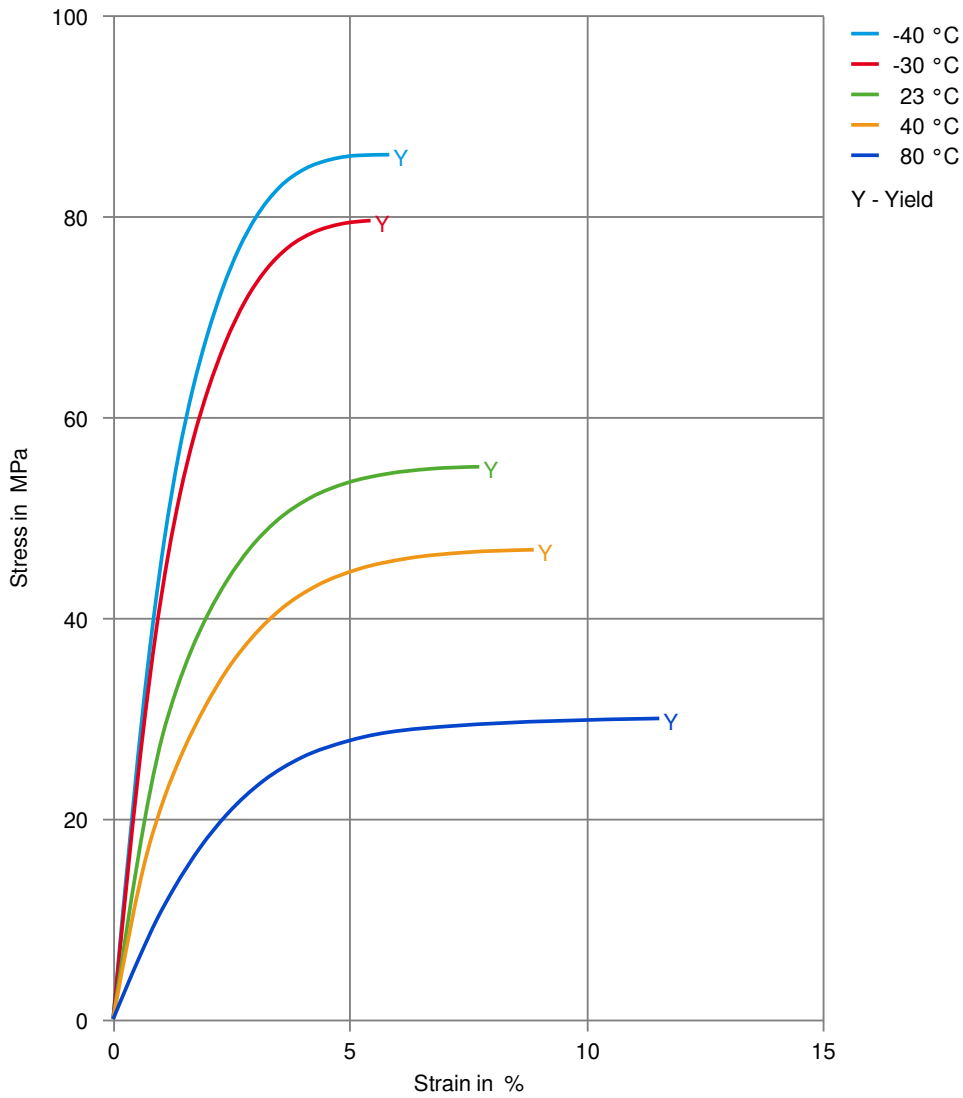
Processing Notes

Pre-Drying

Drying is required for this material to prevent poor appearance and performance of the part.

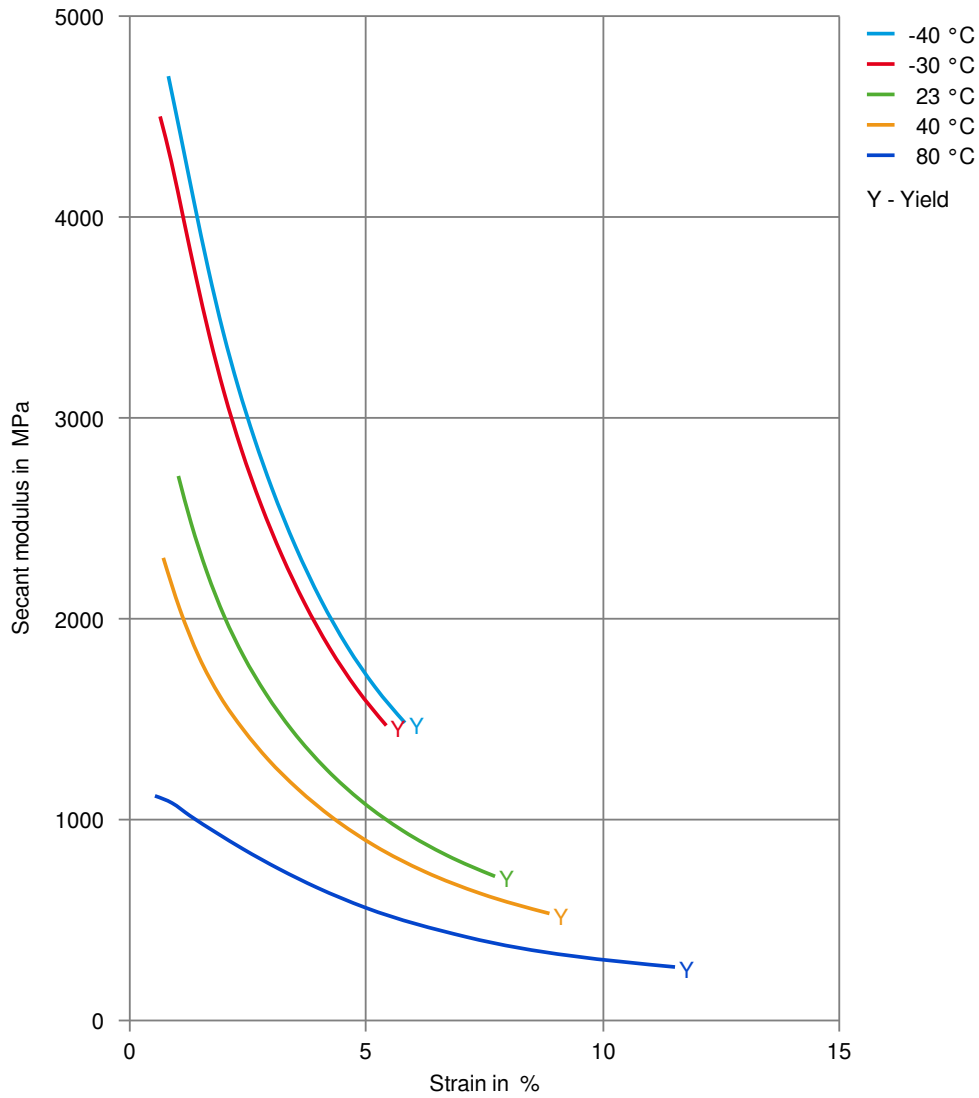
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Stress-strain



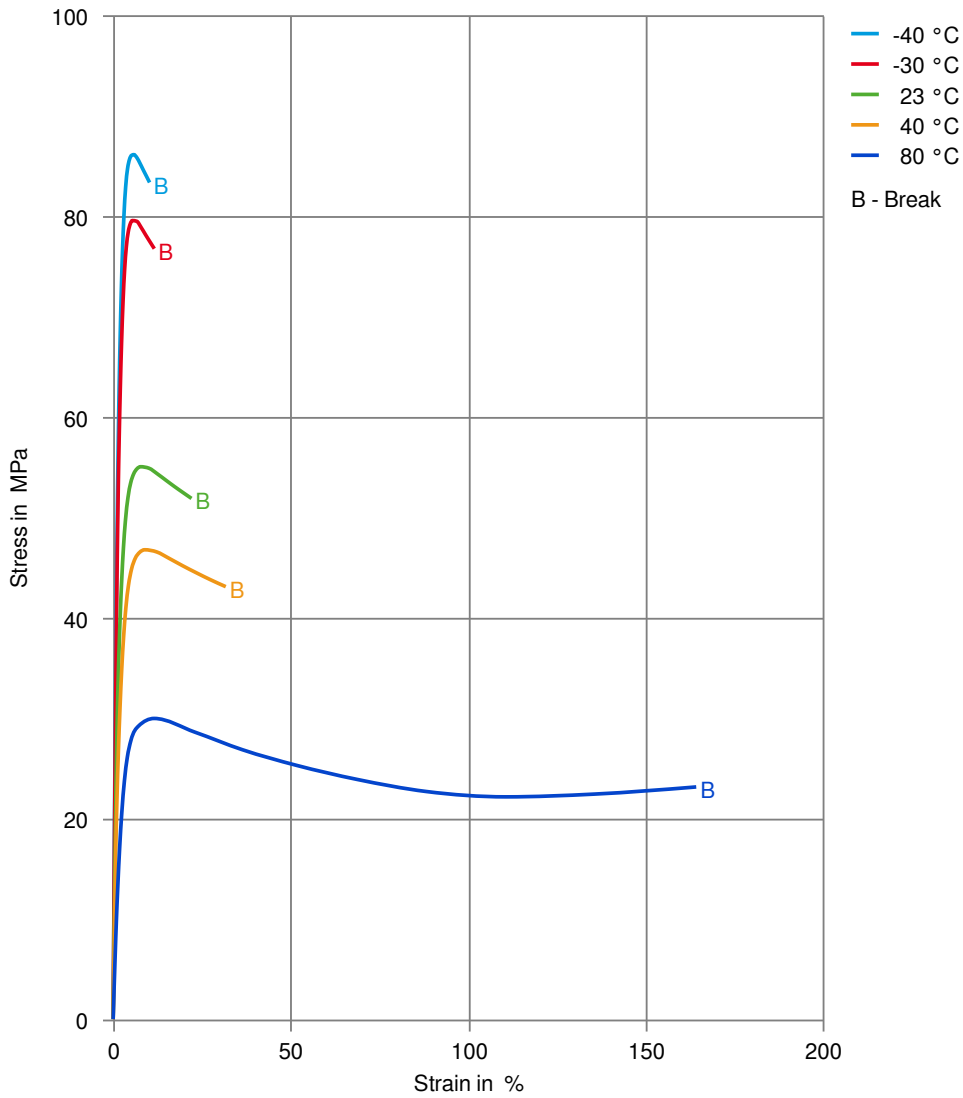
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Secant modulus-strain



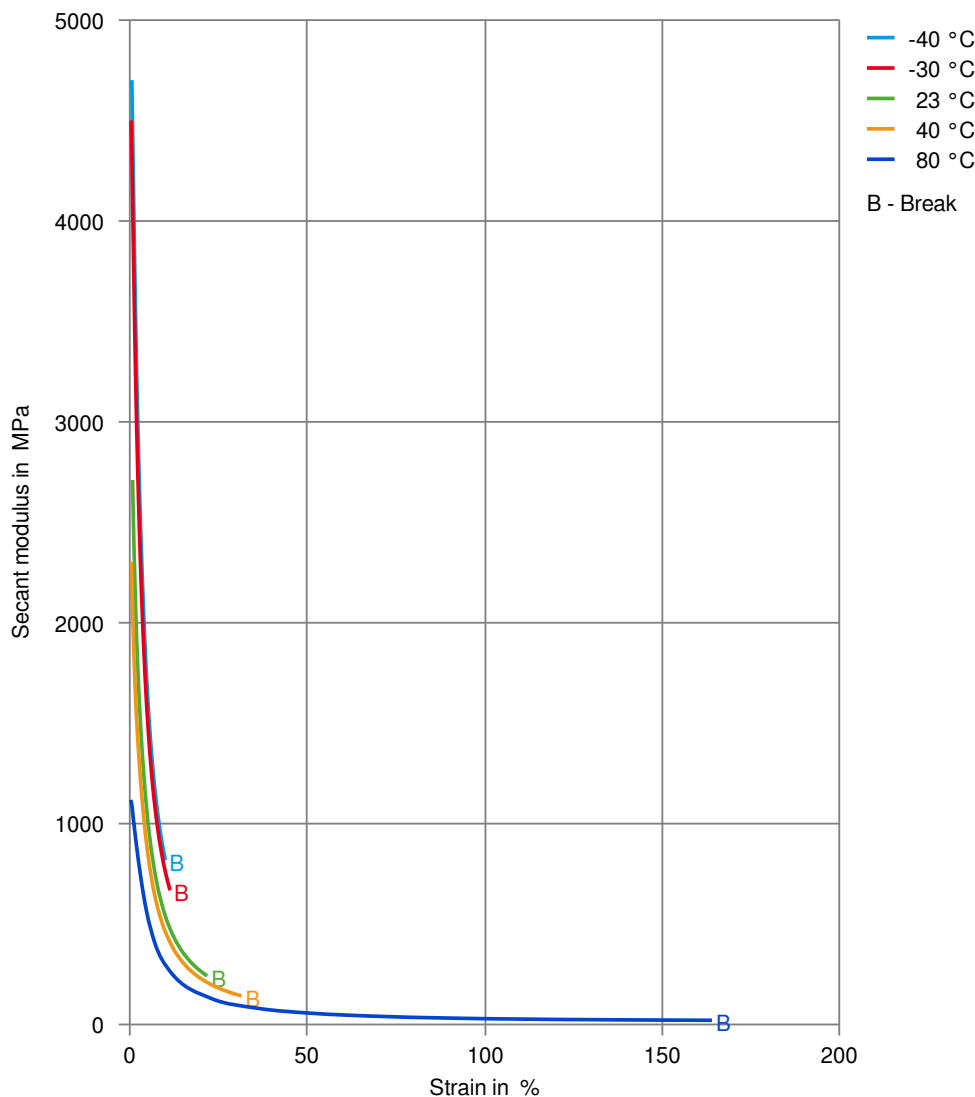
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Stress-strain, 50mm/min



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Secant modulus-strain, 50mm/min



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